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IEEE ELECTRONICS PACKAGING SOCIETY
Malaysia Chapter

EPS Webinar Series 2021/2022

ML/AI for Advanced Semiconductor Packaging & Electronics Manufacturing

In the era of "More than Moore" and heterogeneous integration, many advanced semiconductor packaging processes have presented challenges in manufacturing. Precision alignment has been one of the key capabilities for several advanced technologies for heterogeneous integration, such as 2.5D/3D, optical assembly, etc.

Dr. Shangguan currently advises several innovative companies in the global electronics industry. Previously, he served as Corporate Vice President for Advanced Microelectronics & Manufacturing Engineering at Flex (formerly Flextronics), and as Chief Marketing Officer at STATSChipPAC (currently JCET). Early in his career, Dr. Shangguan spent 10 years with Ford Motor Co. and Visteon Corporation where he held various technical and management responsibilities

Dr. Dongkai Shangguan
Speaker
IEEE and IMAPS Fellow

JOIN US FOR THIS UPCOMING WEBINAR

Date: 2 December 2021 (Thursday)
Time: 10.00-11.00 a.m. (M'sia Time, GMT +8:00)
Platform: CISCO WebEx

REGISTER NOW

(Click the link for registration)
**E-certificates will be provided to all participant*

- Talk will discuss on several important applications of ML/AI in semiconductor packaging, optical assembly, PCB assembly and other areas in electronics manufacturing
- Applications such as traceability, predictive maintenance, productivity improvement, and process optimization, will be discussed
- Presentation focus on the application of ML/AI for precision alignment using real-time data routinely generated by the machine. Future industry perspectives will be outlined.

It is **FREE**! Enroll yourself and join us in this exciting webinar. See you there !